

# Achieving thicker AlGaN material

Researchers explore non-planar growth on a gallium nitride mesa to produce laser diode structures beyond the critical thickness for cracking.

**G**eorgia Institute of Technology and Arizona State University in the USA have used non-planar growth (NPG) of aluminium gallium nitride (AlGaN) on patterned GaN on sapphire to create material with thicknesses beyond critical with a view to ultraviolet laser diodes [Frank Mehnke et al, J. Appl. Phys., v131, p073103, 2022].

Lattice mismatch and thermal expansion mismatch between AlGaN and GaN often lead to cracking of the material from the build up of stress.

The reported experimental critical thicknesses of  $\text{Al}_{0.17}\text{Ga}_{0.83}\text{N}$  and  $\text{Al}_{0.21}\text{Ga}_{0.79}\text{N}$  are less than  $\sim 620\text{nm}$  and  $\sim 200\text{nm}$ , respectively. The Georgia/Arizona work achieved laser diode structures with total AlGaN thickness  $\sim 1.5\mu\text{m}$  without cracking.

The team comments:

"We believe that this approach can also be extended to NPG growth on bulk GaN substrates as well as other tensile-strained semiconductor systems."

The templates for the work consisted of  $2.7\mu\text{m}$ -thick GaN on sapphire, grown by metal-organic chemical vapor deposition (MOCVD). X-ray analysis showed the threading dislocation density in the GaN to be  $\sim 2 \times 10^9/\text{cm}^2$ .

The GaN layer was patterned with  $2\text{mm}$ -long stripe mesas of various widths between  $10\mu\text{m}$  and  $200\mu\text{m}$ , created using photolithography and plasma etch with silicon dioxide masking. The stripes were placed at

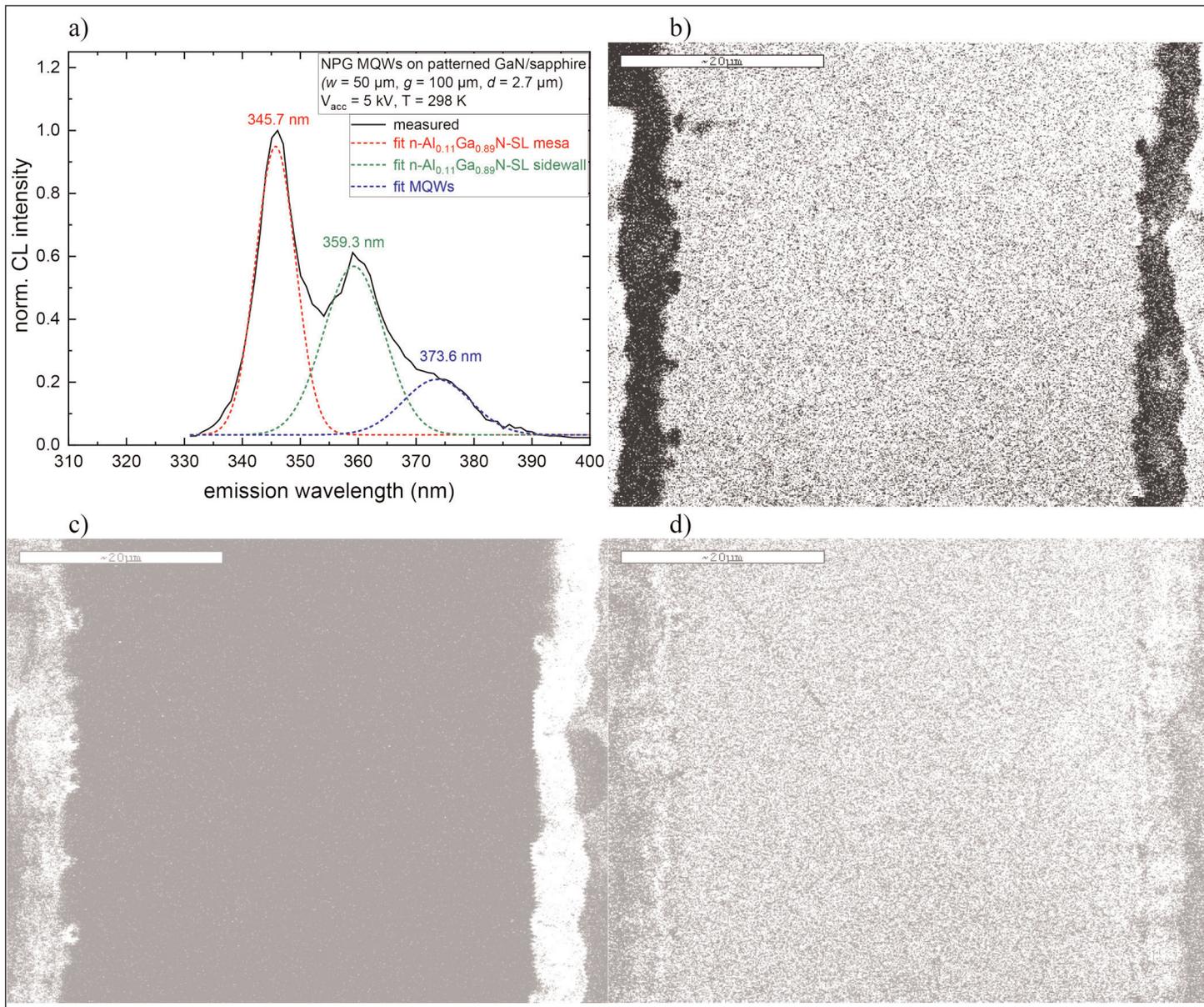
various spacings from  $10\mu\text{m}$  to  $200\mu\text{m}$ . The stripes were oriented along the  $[1\bar{1}00]_{\text{GaN}}$  symmetry direction. The aim was to ease the cleaving of the material for laser facets in the perpendicular  $\{1\bar{1}00\}_{\text{GaN}}$  symmetry plane.

The mesa etch depth varied between  $500\text{nm}$  and  $3000\text{nm}$ . The deepest etch depth ( $3000\text{nm}$ ) cut into the sapphire substrate. The mesa sidewalls were "near vertical". The root-mean-square (rms) roughness was estimated at  $\sim 0.6\text{nm}$  on a  $5\mu\text{m} \times 5\mu\text{m}$  field.

The researchers studied the MOCVD growth of  $5\text{nm}$ -period AlGaN superlattices of various pairings of

Contact	p-GaN	10nm
Cladding	p-AlGaN SL	500nm
Waveguide	p- $\text{Al}_{0.06}\text{Ga}_{0.94}\text{N}$	150nm
Electron block	p- $\text{Al}_{0.3}\text{Ga}_{0.7}\text{N}$	10nm
Cap	$\text{Al}_{0.3}\text{Ga}_{0.7}\text{N}$	20nm
MQW	$2 \times (\text{In}_{0.02}\text{Ga}_{0.98}\text{N}/\text{Al}_{0.09}\text{Ga}_{0.91}\text{N})$	3nm/9nm
Barrier-1	$\text{Al}_{0.09}\text{Ga}_{0.91}\text{N}$	30nm
Waveguide	n- $\text{Al}_{0.06}\text{Ga}_{0.94}\text{N}$	150nm
Cladding	n-AlGaN SL	600nm
Buffer	n-GaN	300nm

Figure 1. Structure of laser diode material.



**Figure 2. (a) CL spectra at room temperature of NPG MQW heterostructure and monochromatic CL maps at (b) 345.7, (c) 359.3 and (d) 373.6nm.**

Al composition: 0.06/0.16, 0.11/0.21, and 0.16/0.26. The average compositions were 0.11, 0.16, and 0.21, respectively.

The researchers found that cracks formed in two stages: first, cracks between the stripes emerged in a  $[11\bar{2}0]$  direction perpendicular to the mesa stripes; later, the cracks formed networks along the  $\langle 11\bar{2}0 \rangle$  symmetry directions.

The researchers comment: "The formation of the first cracks perpendicular to the mesa stripe orientation is most likely caused by an anisotropic strain distribution along the mesa as material can relax toward the mesa edges but is limited in relaxation along the mesa stripe."

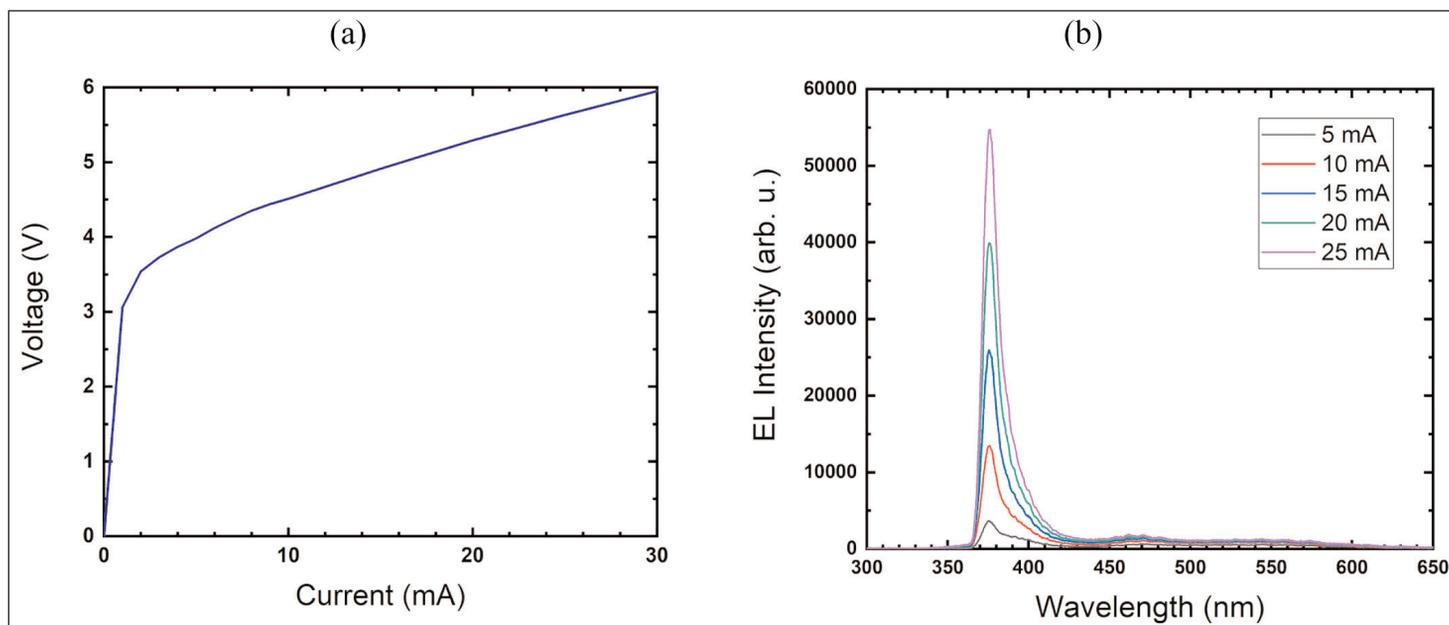
The team found that cracking was primarily avoided by reducing the mesa stripe width.

The researchers used material grown on 2.7- $\mu\text{m}$ -deep mesas (i.e. 3000nm etch depth) with 100 $\mu\text{m}$  gap to

create laser diode heterostructures (Figure 1). The superlattices (SLs) consisted of 5nm-period 0.06/0.16nm (0.11nm) Al content. The total AlGaIn thickness was  $\sim 1470\text{nm}$ , "much larger than the critical layer thickness for these materials," the team comments.

The researchers comment: "This heterostructure design is based upon the modeling of the optical properties of the heterostructure with the goal of increasing the optical confinement factor while not increasing the electrical resistance too much."

Under electron-beam excitation (cathodoluminescence) on material 50 $\mu\text{m}$  mesa widths, the structure emitted light with spectral peaks at 345.7nm, 359.3nm and 373.6nm (Figure 2). The researchers believe that these peaks were associated with emissions from the mesa, sidewall and multiple quantum well (MQW) regions, respectively.



**Figure 3. (a) Voltage-current plot and (b) 300K injection-current-dependent EL spectra of edge emission of a 30µm wide NPG/GaN/sapphire laser diode stripe for various DC drive currents.**

► Fabricated 30µm×1000µm laser diodes emitted 376.8nm electroluminescence (EL) with 13nm full-width at half-maximum (FWHM) at 25mA current injection (Figure 3). No threshold is mentioned, so one presumes

that lasing was not achieved yet. ■

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